

### REMARKS

Claims 1-27 are pending. Claims 19-27 have been canceled without prejudice, retaining the right to file divisional applications thereon. Applicants confirm election of claims 1-18 without traverse for further prosecution on the merits. Claims 1-18 stand rejected under 36 U.S.C. §112. Applicants cordially thank the Examiner for the allowable subject matter indicated with respect to claims 1-18, but for the §112 rejections. Claims 1, 2 and 7 have been amended, leaving claims 1-18 for consideration upon entry of this amendment. Support for the amendments may be found at least in Figures 1-2c and accompanying description in the originally filed specification. No new matter has been added.

#### *Claim Rejections -35 USC § 112*

Claims 1-18 stand rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claim 1 recites the limitation "associated" in line 7. The Examiner alleges that it is not clear how the metallization layer is associated with the bonding pads. Accordingly, claim 1 has been amended to replace "associated" with --corresponding-- in line with the specification describing etching of the passivation layer 50 and a portion of the Cr/Cu/Ni/Au/Cr metallization layer disposed over each bonding pad 26, 48 to form openings 54 "corresponding" with each bonding pad 26, 48, as described on page 6 of the originally filed application.

With respect to claim 2, the Examiner states that "depending" in line 3 is not clear what kind of relationship the claim refers to. The Examiner states that it appears that "depending from" should be substituted with--bonded to--. Accordingly, claim 2 has been amended to replace "depending from" with --bonded to-- as suggested by the Examiner.

With respect to claim 7 recites five depositing steps, the Examiner states that it is not clear where each layer of the five depositing steps is deposited to. Accordingly, claim 7 has been amended to reflect that the first Cr layer is deposited on the substrate and each subsequent layer is deposited on the previous layer.

It is respectfully submitted that all of the §112 rejections have been addressed and cured. Thus, it is respectfully requested that the rejection to claims 1-18 be withdrawn.

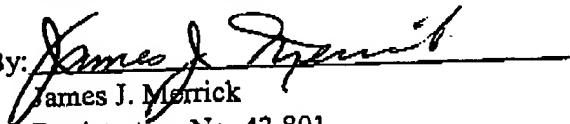
**Conclusion**

Applicants respectfully submit that all outstanding rejections have been addressed and the present application is in condition for allowance. Reconsideration and allowance thereof is most earnestly and respectfully requested.

In the event the Examiner has any queries regarding the presently submitted response, applicants' attorney respectfully requests the courtesy of a telephone conference to discuss any matters in need of attention. If there are any associated or additional charges with respect to this Response or otherwise, please charge them to Deposit Account No. 09-0458 maintained by the Applicants' Assignee.

Respectfully submitted,

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